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Appln. No. 10/532,949
Response dated May 29, 2009 to
Reply to Office Action of March 31, 2009

Amendments to the Claims:

Please amend claims 1, 2, 6 and 7, as follows. The following listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claim 1 (Previously Presented). A holding and conveyance jig for detachably holding and conveying a printed circuit board on which electronic components are mounted or a conductive material laminated plate for manufacturing said printed circuit board, said jig comprising:

a plate which ~~has no electric circuit element and has a~~ weak-adherence adhesive pattern on a surface thereof ~~of the~~ plate; wherein:

said printed circuit board has a conductive portion and a non-conductive portion on a surface thereof ~~of the printed circuit board~~, and said printed circuit board or said conductive material laminated plate is placed and held on the surface of said plate, and

said weak-adherence adhesive pattern is formed at a position corresponding to said non-conductive portion.

Claim 2 (Currently Amended). A holding and conveyance jig

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for detachably holding and conveying a printed circuit board on
which electronic components are mounted or a conductive material
laminated plate for manufacturing said printed circuit board,

5 said jig comprising:

a plate which ~~has no electric circuit element and~~ has a
weak-adherence adhesive layer on a surface thereof ~~of the plate~~;
wherein:

said printed circuit board has a conductive portion and a
10 non-conductive portion on a surface thereof ~~of the printed~~
~~circuit board~~, and said printed circuit board or said conductive
material laminated plate is placed and held on the surface of
said plate, and

a weak-adherence adhesive pattern subjected to surface
15 roughening is formed on a surface of said weak-adherence adhesive
layer at a position corresponding to said conductive portion.

Claim 3 (Previously Presented). The holding and conveyance
jig according to claim 1, wherein said weak-adherence adhesive
pattern has a plurality of thickness regions differing in
thickness from the surface of said plate.

Claim 4 (Previously Presented). The holding and conveyance
jig according to claim 1, wherein said weak-adherence adhesive

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pattern has a plurality of adhesive strength regions differing in adhesive strength.

Claim 5 (Previously Presented). The holding and conveyance jig according to claim 2, wherein a non-adhesive pattern is formed at a position corresponding to said conductive portion on the surface of said weak-adherence adhesive layer.

Claim 6 (Currently Amended). A method of conveying a printed circuit board on which electronic components are mounted and which has ~~having~~ a conductive portion and a non-conductive portion on a surface thereof ~~of the printed circuit board~~ while
5 detachably holding said printed circuit board on a holding and conveyance jig in which a weak-adherence adhesive pattern is provided on a surface of the jig, ~~and no electric circuit element is provided on the surface of the jig,~~ the method comprising the step of:
10 holding said printed circuit board on the surface of said holding and conveyance jig in a manner such that said non-conductive portion is placed by being restricted to a surface of said weak-adherence adhesive pattern.

Claim 7 (Currently Amended). A method of conveying an

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electroconductive material laminated plate for manufacturing a
printed circuit board on which electronic components are mounted
and which has ~~having~~ a conductive portion and a non-conductive
5 portion on a surface thereof ~~of the printed circuit board~~ while
detacably holding said electroconductive material laminated plate
on a holding and conveyance jig in which a weak-adherence
adhesive pattern is provided on a surface of the jig, ~~and no~~
~~electric circuit element is provided on the surface of the jig,~~
10 the method comprising the step of:

holding said electroconductive material laminated plate on
the surface of said holding ~~[[and]]~~ and conveyance jig in a
manner such that a portion intended for formation of said
non-conductive portion is placed by being restricted to a surface
15 of said weak-adherence adhesive pattern.

Claim 8 (Withdrawn). A jig for holding and conveyance
comprising:

- a plate having a weak-adherence adhesive layer on its
surface;
- 5 a printed circuit board having a conductor pattern on its
insulating substrate surface, or an electroconductive material
laminated plate for manufacturing said printed circuit board,
said printed circuit board or said electroconductive material

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laminated plate being placed and held on the surface of said
10 plate,

wherein said weak-adherence adhesive layer is a
fluorine-based resin layer.

Claim 9 (Withdrawn). The jig for holding and conveyance
according to claim 8, wherein said fluorine-based resin layer is
formed so as to hold said printed circuit board or said
electroconductive material laminated plate so that a surface of
5 said conductor pattern or an electroconductive material foil
surface of said electroconductive material laminated plate is
approximately parallel to the surface of said plate.

Claim 10 (Withdrawn). The jig for holding and conveyance
according to claim 8, wherein said fluorine-based resin layer has
a plurality of thickness regions differing in thickness from the
surface of said plate.

Claim 11 (Withdrawn). The jig for holding and conveyance
according to claim 8, wherein said fluorine-based resin layer has
a plurality of adhesive strength regions differing in adhesive
strength.

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Claim 12 (Withdrawn). The jig for holding and conveyance according to claim 8, wherein surface roughening is selectively performed on a region of said fluorine-based resin layer other than a holding portion for holding said printed circuit board or
5 said electroconductive material laminated plate.

Claim 13 (Withdrawn). The jig for holding and conveyance according to any one of claim 8, wherein a plurality of said fluorine-based resin layers are provided on the surface of said plate, and a non-adhesive material layer is provided on a
5 non-formation portion of said fluorine-based resin layers on the surface of said plate.

Claim 14 (Withdrawn). The jig for holding and conveyance according to claim 8, wherein said fluorine-based resin layer has a holding portion for holding said printed circuit board or said electroconductive material laminated plate, and has a
5 non-adhesive layer on a portion other than said holding portion.

Claim 15 (Withdrawn). The jig for holding and conveyance according to claim 8, wherein said fluorine-based resin layer has a hardness (JIS-A) of 100° or lower.

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Claim 16 (Previously Presented). The holding and conveyance jig according to claim 2, wherein said weak-adherence adhesive pattern has a plurality of thickness regions differing in thickness from the surface of said plate.

Claim 17 (Previously Presented). The holding and conveyance jig according to claim 2, wherein said weak-adherence adhesive pattern has a plurality of adhesive strength regions differing in adhesive strength.

Claim 18 (Previously Presented). The holding and conveyance jig according to claim 3, wherein said weak-adherence adhesive pattern has a plurality of adhesive strength regions differing in adhesive strength.

Claim 19 (Previously Presented). The holding and conveyance jig according to claim 16, wherein said weak-adherence adhesive pattern has a plurality of adhesive strength regions differing in adhesive strength.